

ABSTRACT

A CARD BODY, A MANUFACTURING METHOD FOR AN IC CARD, AND THE IC CARD

According to one embodiment, a card body includes a card part onto which an IC module is to be mounted, and a bracket part to support the card part. The card part includes a bevel. The bracket part includes a hole, a first bridge part, a second bridge part, a first break-off line, and a second break-off line. The hole is formed at a circumference of the card part. The first bridge part connects the bracket part and the card part. The second bridge part connects the bracket part and the card part. The second bridge part is provided at a farther position from the bevel than the first bridge part. The first break-off line is provided with a first depth at the first bridge part. The second break-off line is provided with a second depth at the second bridge part. The second depth is shallower than the first depth.

FIG. 1